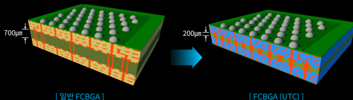
FCBGA (UTC)

개요 OVERVIEW

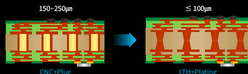
SET 슬림화를 위한 박형 패키지 기판

- 응용분야 : 노트북용 CPU, Tablet PC용 CPU 등



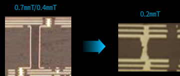
차별화 DIFFERENTIATION

Laser PTH 개발



- 필요기술 : Void-free Fill 도금

박판화



- 필요기술 : 非접촉 기판 구동

주요 사양 KEY SPECIFICATIONS

기판 층수	8~10층
Core 두께	100~200µm
회로 (Line/Space)	9/12µm
Bump pitch	100µm

※ UTC : Ultra Thin Core